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To the Honorable Commissioner of Patents

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Original documents or copy thereof

1 Name of conveying party(ies):
SHYH-MING CHANG, JWO-HUEI JOU
AND CHI-YUAN WU

2 Name and address of receiving party(ies):
INDUSTRIAL TECHNOLOGY RESEARCH INSTITUTE
195 Sec. 4
Chung Hsing Road
Chutung, Hsinchu, Taiwan 310
R.O.C.

TO
09/31/99
05/24/99

Execution Date: March 16, 18 and 23, 1999

Additional name(s) & address(es) attached Yes No

4 Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: 3-23-99

A. Patent Application No(s).

B. Patent No(s)

09/317307

Additional numbers attached? Yes No

5 Name and address of party to whom correspondence concerning document should be mailed:

RANDY W. TUNG
Tung & Associates
838 W. Long Lake Road
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Bloomfield Hills, Michigan 48302

6 Total number of applications and patents involved:
1

7 Total fee (37 CFR 3.41) **\$40.00**

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To the best of my knowledge and belief the foregoing information is true and correct and any attached copy is a true copy of the original document.

Randy W. Tung
Name of Person Signing
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Signature

05-24-99
Date

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Mail documents to be recorded with required cover sheet information to:
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Washington, D.C. 20231

PATENT
REEL: 009997 FRAME: 0326

ASSIGNMENT

WHEREAS, we, ^YSHU^H-MING CHANG, ^WJU^O-HUEI JOU AND CHI-YUAN WU,
have invented certain improvements in METHOD FOR BONDING IC CHIPS HAVING MULTI-
LAYERED BUMPS WITH CORRUGATED SURFACES AND DEVICES FORMED for which
we are about to make application for Letters Patent of the United States; and

WHEREAS, INDUSTRIAL TECHNOLOGY RESEARCH INSTITUTE of 195 Sec.
4, Chung Hsing Road, Chutung, Hsinchu, Taiwan 310, R.O.C, is desirous of acquiring the entire
right, title and interest in and to said invention;

NOW, THEREFORE, in consideration of One Dollar (\$1.00) and other good and
valuable consideration, the receipt of which is hereby acknowledged, we, ^YSHU^H-MING CHANG,
^WJU^O-HUEI JOU AND CHI-YUAN WU, by these presents, do hereby sell, assign and transfer unto
the said corporation and its assigns, for the territory of the United States of America and all foreign
countries, the entire right, title and interest, including all priority rights under the International
Convention associated with each country of the Union, in and to said invention as described in the
patent application executed by us on the ^{16, 18}₂₃ day of March, 1999, preparatory
to obtaining Letters Patent of the United States thereon, and in and to said application and any
Letters Patent that may be granted in pursuance of said application and any divisional, continuation
or continuation-in-part application thereof, and in and to any reissue of any such patent, and in and
to any patent applications which may be filed on said invention in countries foreign to the United

States and any Letters Patent granted thereon.

We further authorize said corporation to apply for foreign patents on said invention in its own name or through its designees, including subsidiaries, related companies or assignees, under the International Convention or otherwise, and we further agree to execute all papers, including those required for the United States and foreign applications, and to perform such other proper acts as said corporation or its designees the rights herein assigned.

Shyh-Ming Chung

SHYH-MING CHANG
Y

Jou-Huei Jou

JOU-HUEI JOU
↓
W

CHI-YUAN WU

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